

# Product data sheet

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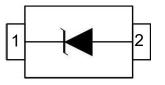


## PACKAGE OUTLINE



SOD-523

#### **PIN CONFIGURATION**



#### **FEATURES**

- ♦ IEC61000-4-2 Level 4 ESD Protection
- $\diamond$  Protects one directional I/O line
- ♦ Low clamping voltage
- $\diamond$  Working voltages : 24V
- ♦ Low leakage current

#### MACHANICAL DATA

- ♦ SOD-523 package
- ♦ Flammability Rating: UL 94V-0
- ♦ Packaging: Tape and Reel
- $\diamond$  High temperature soldering guaranteed: 260  $^\circ\! \mathbb{C}/10s$
- $\diamond$  Reel size: 7 inch

## APPLICATIONS

- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- $\diamond$  Notebooks, Desktops, and Servers
- Portable Instrumentation
- $\diamond$  Peripherals
- ♦ Pagers

ABSOLUTE MAXIMUM RATING					
Symbol	Parameter	Value	Unit		
	ESD per IEC 61000-4-2 (Air)	±15			
V <sub>ESD</sub>	ESD per IEC 61000-4-2 (Contact)	±8	kV		
PD	Total Power Dissipation on FR-5 Board (Note 1) @ Ta=25 <sup>+</sup> C	150	mW		
T <sub>OPT</sub>	Operating Temperature	-55~125	°C		
T <sub>STG</sub>	Storage Temperature	-55~150	°C		

These ratings are limiting values above which the serviceability of the diode may be impaired. Note 1: FR-5=1.0x0.75x0.62 in.

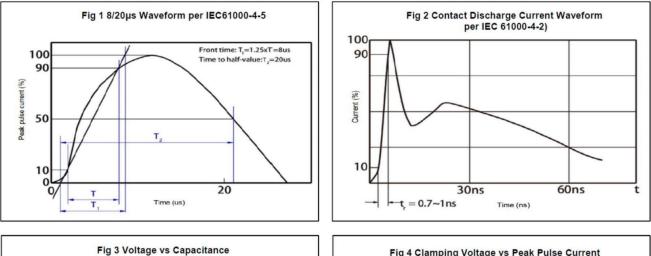


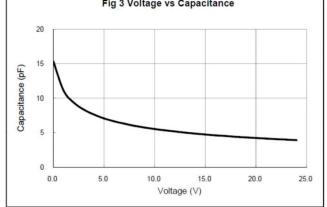
ESD	95Z	22	4-1	MS	5 H	F	

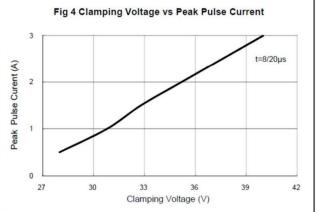
Semiconductor Compiance

ELECTRICAL CHARACTERISTICS (Tamb=25°C)						
Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V <sub>RWM</sub>	Reverse Working Voltage				24	V
V <sub>BR</sub>	Reverse Breakdown Voltage	I <sub>T</sub> = 1mA	26			V
I <sub>R</sub>	Reverse Leakage Current	V <sub>RWM</sub> = 24V			1	μA
Vc	Clamping Voltage	$I_{PP} = 1A, t_p = 8/20 \mu s$			35	V
CJ	Junction Capacitance	$V_R = 0V$ , f = 1MHz			50	pF

## ELECTRICAL CHARACTERISTICS CURVE



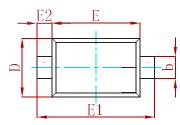


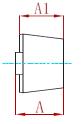


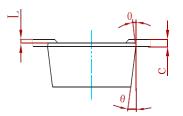




# PACKAGE MECHANICAL DATA

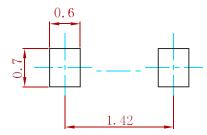






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
A	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200	REF	0.008 REF		
L	0.010	0.070	0.001	0.003	
0	7° F	REF	7° REF		

# Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
ESD5Z24-MS	SOD-523	3000





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